

## AMENDMENT



In response to the Office Action of November 25, 2002, please amend the above-identified application as follows:

**In the Claims:**

Please amend claim 1 as follows:

1. (AMENDED) A polishing apparatus having a ditched ring for preventing wrinkling of a polishing pad that borders a substrate during chemical mechanical polishing of a substrate, comprising:

a rotatable head assembly having a shallow recessed face adapted to centerly hold a substrate;

a non-rotating cylindrical actuator assembly coaxially oriented about the outer edge of said rotary polishing head assembly;

a rotary polishing platen having a polishing pad surface facing said substrate;

a polishing slurry containing a mechanical abrasive deposited on said polishing pad;

a ditched ring removably attached to a bottom surface of said non-rotary cylindrical actuator assembly, said ditched ring having a bottom surface with a multiplicity of conduit grooves formed therein, said conduit grooves permitting a boundary layer of abrasive slurry to flow unimpeded to a rotating substrate while

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a space

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preventing wrinkling of said polishing pad.

*French*

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